

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: LCP BLACK,UL94V-0.
- 1.2 CONTACT: PHOSPHOR BRONZE,GOLD (SEE P/N) PLATED IN CONTACT AREA, 80u" MIN MATTE TIN PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS,80u" MIN. MATTE TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 0.5A;
- 2.2 VOLTAGE RATING: 50V AC/DC
- 2.3 DIELECTRIC WITHSTANDING VOLTAGE: 200V AC/MINUTE.
- 2.4 CONTACT RESISTANCE: 80mΩ MAX.
- 2.5 INSULATION RESISTANCE: 500MΩ MIN.
- 2.6 OPERATION TEMPERATURE:-40°C TO +105°C.

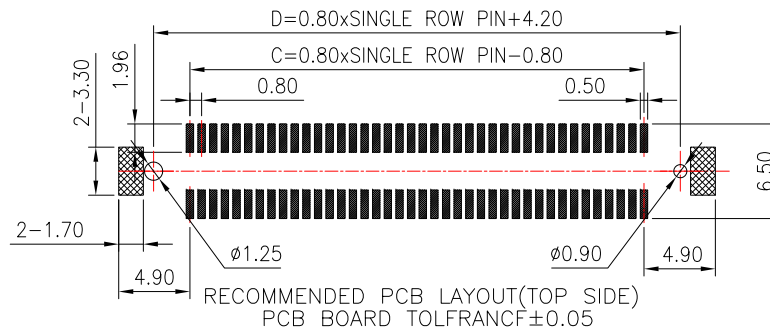
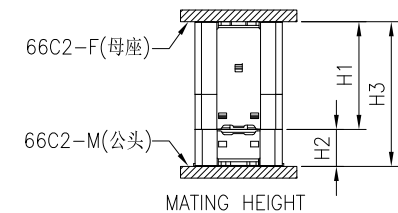
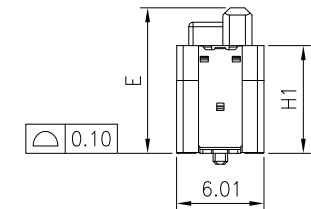
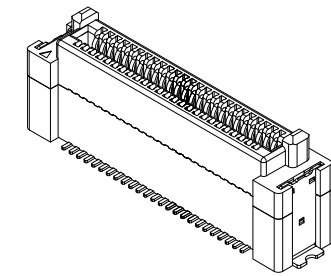
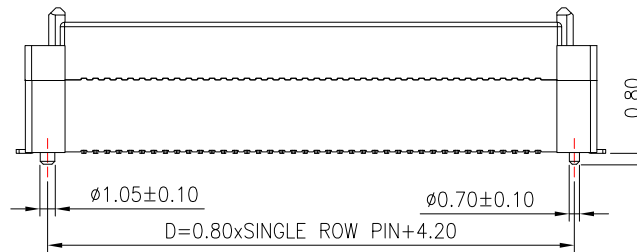
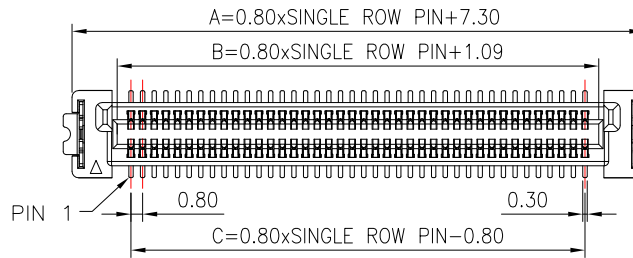
3.ORDER INFORMATION:

66C2-F XXX XX XXX R 01

Pin数码 SEE TABLE	端子电镀: S0=Gold Flash/Tin(半金锡) S1=1u" Gold/Tin S2=3u" Gold/Tin S3=5u" Gold/Tin S4=10u" Gold/Tin S5=15u" Gold/Tin S6=30u" Gold/Tin	塑胶高度: 050=5.0mm("E") 060=6.0mm("E") 100=10.0mm("E")	包装方式: R=TAPE REEL
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TABLE1:

No. OF PIN	A	B	C	D
010:2x5PIN	11.30	5.09	3.20	8.20
020:2x10PIN	15.30	9.09	7.20	12.20
030:2x15PIN	19.30	13.09	11.20	16.20
040:2x20PIN	23.30	17.09	15.20	20.20
050:2x25PIN	27.30	21.09	19.20	24.20
060:2x30PIN	31.30	25.09	23.20	28.20
080:2x40PIN	39.30	33.09	31.20	36.20
100:2x50PIN	47.30	41.09	39.20	44.20
140:2x70PIN	63.30	57.09	55.20	60.20



MATING HEIGHT	E	H1	H2	H3
5.00mm	5.00	2.45	2.55	5.00
10.00mm			7.55	10.00
15.00mm			12.55	15.00
6.00mm	6.00	3.45	2.55	6.00
11.00mm			7.55	11.00
16.00mm			12.55	16.00
10.00mm	10.00	7.45	2.55	10.00
15.00mm			7.55	15.00
20.00mm			12.55	20.00

OPERATION		DRAW	WLY	2019.08.30
X.X	±0.40	DESIGN	Jensen	2019.08.30
X.XX	±0.25	CHECK	Jack	2019.08.30
X.XXX	±0.15	APPROVE	Andy	2019.08.30
Angle	±3°	UNIT	mm	SCALE 1:1
DIM.	TOL	UNIT	mm	SCALE 1:1

SOLEPIN 东莞市硕品电子有限公司
Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
AO		NEW		

SIZE	A4	PART NO.	66C2-FXXXXXXXR01
SHEET	1/1	TITLE:	BTB PITCH 0.8mm 母座直立式SMT TYPE
PROJ.	PROJ.	DRAW NO.	SP-095

客户图

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- 2.5 INSULATION RESISTANCE: 500MΩ MIN.
- 2.6 OPERATION TEMPERATURE: -40°C TO +105°C.

3.ORDER INFORMATION:

66C2-M XXX XX XXX R 01

Pin数码	端子电镀:	塑胶高度:	包装方式:
SEE TABLE	S0=Gold Flash/Tin	045=4.50mm("E")	R=TAPE REEL
	S1=1u" Gold/Tin	095=9.50mm("E")	
	S2=3u" Gold/Tin	145=14.50mm("E")	
	S3=5u" Gold/Tin		
	S4=10u" Gold/Tin		
	S5=15u" Gold/Tin		
	S6=30u" Gold/Tin		

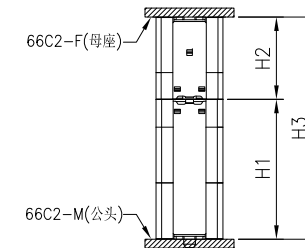
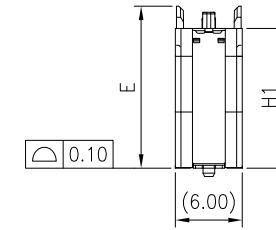
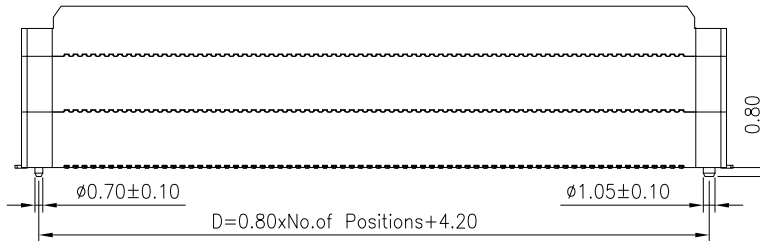
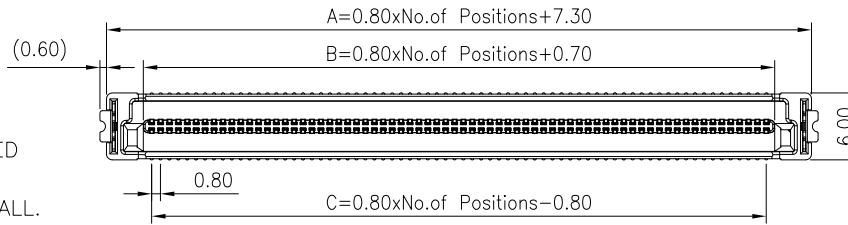
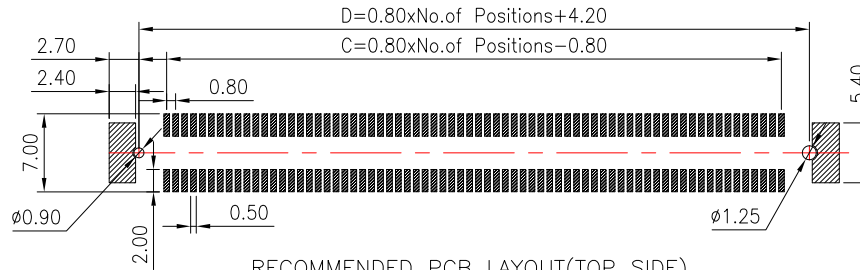


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050:2x25PIN	27.30	20.70	19.20	24.20
060:2x30PIN	31.30	24.70	23.20	28.20
080:2x40PIN	39.30	32.70	31.20	36.20
100:2x50PIN	47.30	40.70	39.20	44.20
140:2x70PIN	63.30	56.70	55.20	60.20



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF±0.05

MATING HEIGHT	E	H1	H2	H3
5.00mm			2.45	5.00
6.00mm	4.55	2.55	3.45	6.00
10.00mm			7.45	10.00
10.00mm			2.45	10.00
11.00mm	9.55	7.55	3.45	11.00
15.00mm			7.45	15.00
15.00mm			2.45	15.00
16.00mm	14.55	12.55	3.45	16.00
20.00mm			7.45	20.00

		OPERATION		DRAW		WLY		2021.03.21		SOLEPIN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.				
		X.X	±0.40	DESIGN		Jensen		2021.03.21						
		X.XX	±0.25	CHECK		Jack		2021.03.21		SIZE	A4	PART NO.	66C2-MXXXXXXXXR01	
AO		NEW		APPROVE		Andy		2021.03.21		SHEET	1/1	TITLE:	0.8mm BTB 公头直立式SMT TYPE	
REV	DATE	MODIFICATION DESCRIPTION		CHANGE	APPROVE	DIM.	TOL	UNIT	mm	SCALE	1:1	PROJ.	DRAW NO.	SP-265